

EV Group Scores Big with Triple Crown Win in Customer Satisfaction Survey – July 10, 2023

semiconductor packaging news

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July 10, 2023

Will China's Reliance on Taiwanese Chips Prevent a War?

Semiconductors enable modern life by providing the computing power for everything from phones to cars, televisions, washing machines, and microwaves. Although these small chips were invented in the United States, the world's leading chips are still designed domestically, and U.S. companies continue to produce specialized tools needed to manufacture semiconductors, Taiwan occupies a dominant ...



Council on Foreign Relations

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Ontos Equipment Systems

Chipmakers should partner with Western firms

Taiwanese semiconductor companies should deepen their partnerships with US and European companies to make an impact on the world's supply chains amid a heightened ...

Taipei Times

Dispositioning Hermetic Microelectronic Components With High Internal Moisture

This white paper presents four options for dispositioning hermetic electronic components non-compliant on internal water vapor content.

Technical Paper

TSMC unfazed by Chinese controls

Taiwan Semiconductor Manufacturing Co (TSMC) said it did not expect any direct effect on its production caused by China's latest export controls on two rare metals essential ...

Taipei Times

Technical Papers

- [Process Considerations for Defluxing Ultra-Fine Pitch Die on CoWs](#)
- [Vacuum FAR Technology For 15 microns and Below Advanced Packaging](#)
- [Heterogeneous IC Packaging: Optimizing Performance And Cost](#)
- [Improving SiC Power Devices with Laser Ohmic Contact Formation](#)
- [Defluxing of Copper Pillar Bumped Flip-Chips](#)
- [Functional testing of 0.3mm pitch WLP](#)
- [Vacuum Fluxless Reflow Technology for Fine Pitch Interconnect Bumping Applications](#)

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Test Your Knowledge

How many times is the capacity of a pipe increased if the diameter is doubled?

See answer below.



Press Releases

EV Group Scores Big with Triple Crown Win in Customer Satisfaction Survey

EV Group announced that it has once again been voted by customers as one of the 10 BEST Focused Suppliers of Chip Making Equipment ...
EV Group

Deutsches Museum in Munich hosts ZEISS Research Award 2023 ceremony

ZEISS presented two research awards to a total of four scientists in ceremonial style. Prof. Dr. Immanuel Bloch was the recipient ...
ZEISS

Nano Dimension Announces Sale to the Univ. of Stuttgart AME DragonFly® IV System

Nano Dimension Ltd. announced that it has sold its DragonFly® IV system to the University of Stuttgart. Nano Dimension's most advanced ...
Nano Dimension Ltd.

Siemens extends support for Samsung Foundry's latest process technologies

Siemens Digital Industries Software announced at the Samsung Advanced Foundry Ecosystem (SAFE) Forum North America 2023 a range ...
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[Chipmakers report strong revenue growth](#)

Contract chipmakers United Microelectronics Corp (UMC) and Vanguard International Semiconductor Corp reported better-than-expected revenue growth last quarter, amid ...
Taipei Times

[Chip war may thwart Shanghai plans to build AI hub](#)

The Shanghai government is stepping up its efforts to attract artificial intelligence (AI) talent and investments and improve regulations with the objective of building a world ...
Asia Times

[Logging 3 Big Lessons From the Supply-Chain Crisis](#)

For the last two years, multiple industries have been severely impacted by a shortage of electronic components. Regula, as global developer of identity-verification solutions ...
EE Times

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Quote of the Day

"Do not give advice that has not been seasoned
by your own performance."
Henry Haskins

[Dicing Die-Attach Film \(DDAF\) or Dicing Die-Attach Tape \(DDAT\)](#)

AI Technology pioneered the
use of flexible die-attach film
and paste adhesives for larger
chip and die bonding. We now
have extended our adhesive line. See more
A.I. Technology, Inc.



[EZ-FLO High Precision Dispense Tips](#)

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resulting smoother internal
profile enhances material flow and
consistency. Learn more.
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What Year Was It?

[Monkey Trial Begins](#)

In Dayton, Tennessee, the so-called
"Monkey Trial" begins with John
Thomas Scopes, a young high
school science teacher, accused of
teaching evolution in violation of a Tennessee
state law.



[The day was Jul 10. What year was it?](#)

[Week In Review: Semiconductor Manufacturing, Test](#)

China retaliated against a U.S. embargo on advanced semiconductor equipment exports by
restricting exports of gallium and germanium. Both metals are widely used in ...
Semiconductor Engineering

[Samsung estimates profits plunged 96% in the second quarter](#)

Samsung Electronics said it expects a 96% profit plunge in the second quarter of 2023 as weak
demand for memory chips persists. The world's largest dynamic random ...
CNBC

[Curbing Automotive Cybersecurity Attacks](#)

The relentless cyberattacks on the automotive sector are not limited to vehicles and have an
impact on the entire automotive supply chain, so the pressure is on ...
Semiconductor Engineering

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[ChatGPT's explosive growth shows first decline in traffic since launch](#)

ChatGPT, the wildly popular artificial intelligence (AI) chatbot launched in November, saw
monthly traffic to its website and unique visitors decline for the first time ever ...
South China Morning Post

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Cartoon of the Day





"If I talk to you about life insurance, I can write off this vacation as a business expense."
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Calendar

- [Jul 10, 2023: Overview of semiconductor manufacturing seminar/San Francisco/ during Semicon West](#)
- [Jul 11, 2023: SEMICON West](#)
- [Jul 11, 2023: FLEX Conference & Exhibition](#)
- [Aug 21, 2023: Overview of semiconductor manufacturing webinar for American attendees](#)

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Essential Inspection Requirements in the Era of Convergence

Herein, learn ways to optimize processes and boost quality as advanced packages and board assembly converge.
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Test Your Knowledge Answer

How many times is the capacity of a pipe increased if the diameter is doubled?
Answer: Four

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